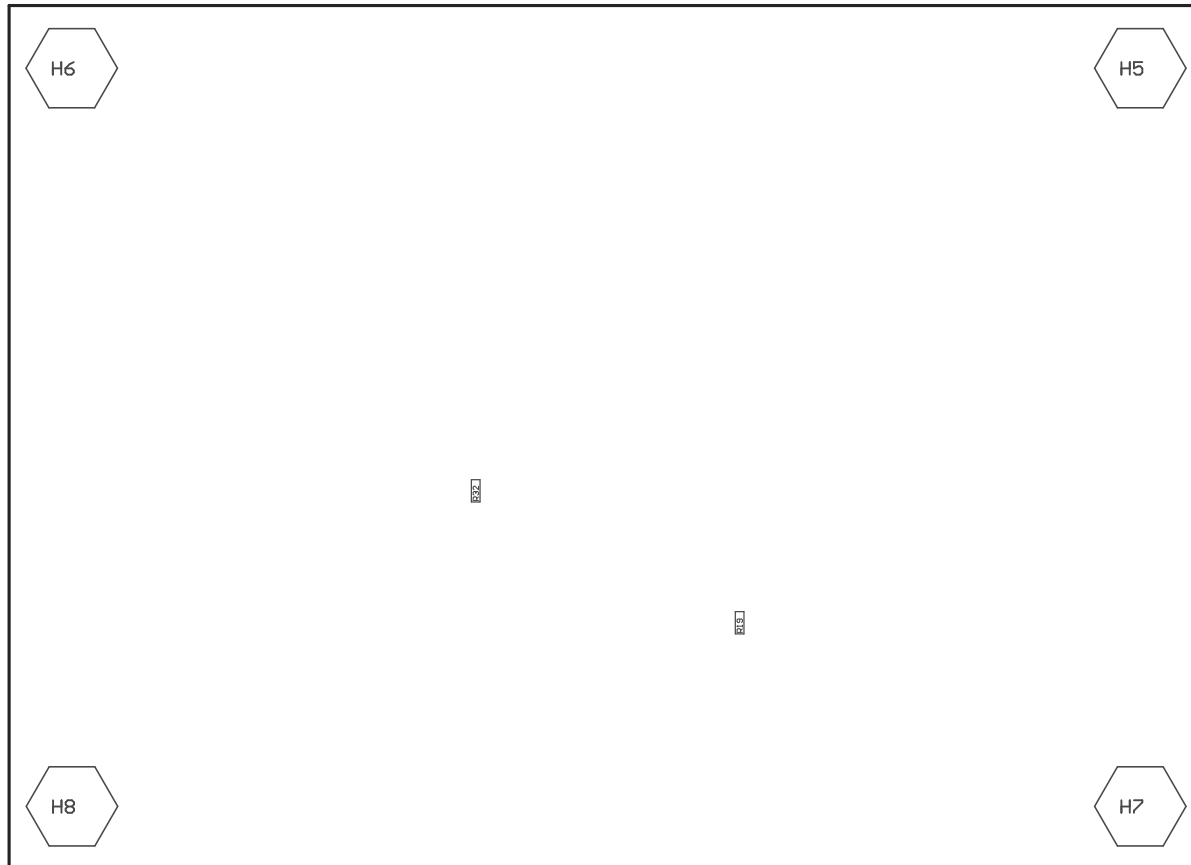


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP21112	REV: A	SVN REV: Not In VersionControl
	TID #: PMP21112		
PLOT NAME = Top Assembly Drawing	GENERATED : 12/18/2017 10:23:34 AM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP21112	REV: A	SVN REV: Not In VersionControl
	TID #: PMP21112		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 12/18/2017 10:23:36 AM		TEXAS INSTRUMENTS

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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